



## **GLAST Large Area Telescope:**

# Electronics, Data Acquisition & Flight Software W.B.S 4.1.7

#### June Status 06-30-04

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## TEM & TEM-PS (1)

	Start/Status	End/Release
Fab Drawing Release		Done
Vendor: Enclosure Fabrication (all 21)	Received all TEM enclosures, TPS due 7/7	7/7
Vendor: PCB Fabrication (4 first articles, plus 18)	Jun 29 started fab	Jul 7
All components in (risk item), see next slide		Jul 15 (Aug 8?)
Test-plan/procedures	Final draft	Jul 1
TC/Vibration/TV/EMI procedures (EMI plan is risk)	Final draft, EMI only first draft	Jul 15
Vendor: Assembly (3 first article, one qual, TWR A &B); TC & vibration. Deliver box to SLAC	July 15 (Aug 8?)	Aug 20
TV (5d); Dyn. Burn-in (5d); EMI (5d)	Aug 20	Sep 15
RFI TWR A	Sep 15	
Vendor: Assembly (19; 15 + 4 spare); deliver box to SLAC **	Sep 1	Oct 1
Flight Acceptance Test	Oct 1	
RFI	Nov 1; sets of 2 with 2 weeks lag	Jan 15

**V2** 



- Component delivery of two Zener diodes.
  - Were ordered 10/1/03, original due date March 04. First delayed to July 22, now August 8. Investigating whether we can get them earlier by accepting them ahead of completion of Group B testing. (Nick is in contact with Microsemi).
- ACTEL FPGA programming (done at ACTEL) and then lead-forming at separate vendor. SOW for lead-forming in review, contract needs to be placed.
- Program for ACTEL can only be finalized when engineer is back from vacation (week after July 4). (Back-flow pressure had minor change)
- Found some CRYSTEK connectors with internal shorts, albeit not from flight order, but from EGSE lot. Should probably test connectors for shorts before assembly.
  - Sent one connector with shorts to Nick Virmani for investigation
  - SLAC QA is in contact with Crystek to get information
- Poly-switches in screening at GSFC, expect them back before July 15.
- Technical meeting with SLAC personnel at assembly vendor today to discuss technical details. Will send test-stands in week after July 4. Then send Dave N. (TPS) and Leonid S. (TEM) to get both test-stands ready.

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**V2** 



- TEM ASIC's test & dynamic burn-in
  - Tested/burned-in/tested 16 GTCC's and 8 GCCC's. No failure after burn-in
  - New batch of 32 GTCC's and 16 GCCC's will start burn-in 6/30.
    - Need 24 GTCC's and 12 GCCC's for 3 first-article TEM's
  - After that burn-in will ramp up using x4 burn-in boards
- GLTC ASIC's (for GASU)
  - Burn-in & test fixture assembled, test program in debug



### GASU & GASU-PS & PDU

	Start/Status	End/Release
Fab Drawing Release (all mechanical GASU drawings were submitted)		July 15
Vendor: Enclosure Fabrication (all 3, qual/flight/spare)	Aug 15	Sep 30
Vendor: PCB Fabrication (all 6 plus 4 spare)	Sept 15	Sep 30
All components in		Sep 30
Test-plan/procedures	now	Aug 30
TC/Vibration/TV/EMI procedures (EMI plan is risk)	now	Sep 30
Vendor: Assembly (first article, qual; deliver box to SLAC)	Sep 30	Oct 30
TC (1d); Vibration (2d); TV (5d); Dyn. Burn-in (5d); EMI (5d)	Oct 30	Nov 30
Done Qual	Nov 30	
Vendor: Assembly (2; 1 + 1 spare); deliver box to SLAC **	Nov 15	Dec 15
Flight Acceptance Test	Dec 15	Jan 19
RFI	Jan 19	

To be done:

- PDU common-mode filter, test with SAI PRU (week after July 4)
- ACD power-switch & monitoring circuit (done, modulo a few resistor changes)
- More testing of trigger & event-builder

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**V2** 

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#### SIU/EPU

	Start/Status	End/Release
Fab Drawing Release (all mechanical drawings were submitted)		Aug 15
Vendor: Enclosure Fabrication (all 8, qual (1) /flight (5) /spare (2))	Aug 30	Oct 15
Vendor: PCB Fabrication (all 10 plus 2 spare)	Oct 1	Oct 15
All components in (Issue: Oscillator, see below)		Oct 15
Test-plan/procedures	now	Sep 15
TC/Vibration/TV/EMI procedures (EMI plan is risk)	now	Oct 15
Vendor: Assembly (first article, qual; deliver boards to SLAC)	Oct 15	Nov 30
TC (1d); Vibration (2d); TV (5d); Dyn. Burn-in (5d); EMI (5d)	Nov 30	Jan 15
Done Qual	Jan 15	
Vendor: Assembly; deliver boards to SLAC	Jan 1	Feb 15
Flight Acceptance Test	Feb 15	Mar 30
RFI	Mar 30	

- To be done:
  - Figure out details of test-plan/procedure for each PCI module
  - PCI code/P&R tayloring to make PCI standard-timing in 72 series (almost done)
  - Test LCB FPGA slave interface code function (is used in EPU)
  - Investigate occasional SIB EEPROM first-address corruption when power-up
  - More testing
- Issue: delivery of 48-MHz oscillator for SIB: now Jan 5 delivery date. Working on the problem)

**V2** 



#### **EGSE- GASU**

- Boxes with 3 versions of DAQ boards
  - Version 1's with reprogrammable FPGA's at
    - ISIS (does not have science interf., but everything else) might not be used anymore see below
    - GSFC ACD (G3#1), used for SW development. Only primary is being used. Tobe shipped back to SLAC
  - Version 2's with one-time programmable ACTEL's at
    - GSFC ACD (G3#2) (Prime&Red)
    - GSFC ACD (G3#3) (Prime&Red)
    - Test-bed (Prime&Red)
    - FSW (Prime) used for ACD software rate-counter code test
    - ISIS (Prime) connected to SIU crate, trying to get LATTE to work with SIU/GASU
    - (New power-switching/current limiting circuit as well as current monitoring circuit were designed/built/tested/incorporated since last meeting)
  - Version 3 with layout changed to incorporate power-switching/monitoring mods (version 2 had daughter-card)
    - 30 boards back from fab
    - 1 board loaded
    - 5 additional board due back from loading July 6
    - GSFC ACD (G3#4) expected to be shipped week after Jul 6.
    - ISIS replacement for prime-only box
    - GSFC ACD (G3#5) for TV: need version 1 enclosure back and then incorporate version 3 boards)
    - I&T (2)
    - FSW (2)
    - DAQ (2)
    - spare (1)



## **EGSE- PDU**

- 1 on Test-bed
- 1 given to ISIS
- Fabricated 10 more boards
  - In loading (2 per enclosure)
  - Available mid/end of July
  - FSW/DAQ (2)
  - I&T (1)
  - spare (1)

## EGSE-TEM

- CAL:
  - 6 at NRL (5 for AFEE test, 1 for TV)
  - 1 needs to come back briefly for shorted connector fix/retest
  - 1 has apparently more noise on one of 4 connectors, but can't be....need to check
  - 4 more for TV in staking/coating, another week before ready.
  - Owe 2 more after that?
- TKR:
  - 1 in building 33 used for MCM screening
  - 4 in Italy (one had grounding problem but was fixed with replacement cable)
  - 1 (and only one?) for TV to be shipped 2<sup>nd</sup> week of July
  - Owe 2 more?
- testbed:
  - has 16
- I&T:
  - received one for mini-tower
- Potential Issue: having enough Motorola CPU boards (also used on ASIC tester at SLAC, will be used for ASIC qual at GSFC, TEM & TPS set-ups at TEM/TPS assembly house, more FSW stations, additional EGSE stations since order)



## EGSE SIU/EPU

- Crates
  - Crates are being used by Testbed/FSW for FSW development/test
  - Assembled two more crates,
    - 1 to be used for ISIS, being tested
    - 1 in testing, goes to NRL
  - BAE750 boards
    - Received all ordered boards (have total of 8)
    - Two additional ones which were to be ordered can't be purchased anymore
      - However BAE will instead be loaning 2 boards for a while....

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- All Front-End Simulators (40) installed on testbed
  - In commissioning
- All 16 TEM & TEM-PS installed on test-bed
  - Being tested
- GASU/PDU/SIU installed on test-bed
- Harness
- Testbed being used for SAI PRU test/debug this week for roadshow next week.



## Threads to maintain schedule/cost

- Connector savers (\$100k just for TEMs)
- Lead-forming (\$40k)
- EGSE cost (cables very expensive, paid substantial expedite fees)
- TEM assembly more than expected (many QA clauses)



## Schedule/Budget

- Total budget: \$21,685
- Work Scheduled up to date: \$16,279
- Work Performed: \$15,120
- Actuals: \$14,626
- Schedule Variance \$-1,159k (-7.9%)
  - Qual/Flight work should have been started, reflects current status
- Cost Variance: \$494k (3.4%)
  - EGSE Labor over budget (26-00068)
  - FSW labor seems under budget, but that is misleading because new FSW PCMS is only being included next month (passed CCB)